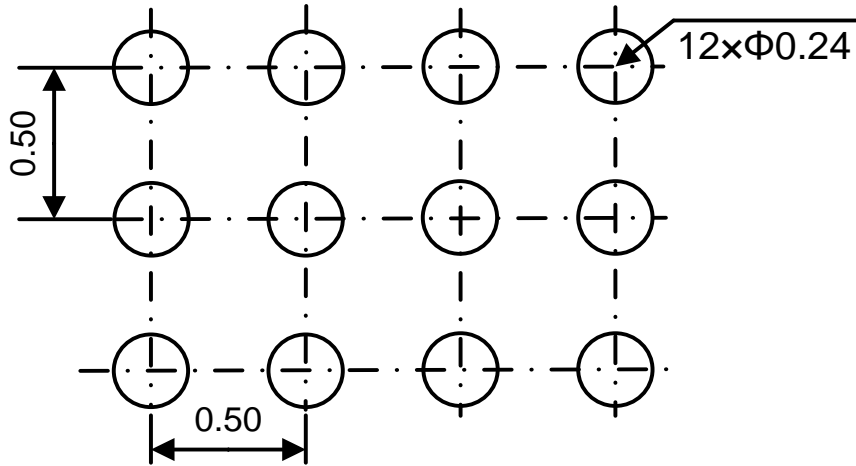


CSP12 1.9×1.4

Land Pattern (101-1914-12)



NOTES:

1. Bump is Lead Free Sn/Ag/Cu.
2. Unit: mm.
3. Non-solder mask defined copper landing pad.
4. Laser Mark on silicon die back; back-lapped.